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(54) **MOUNTING OF CAPACITORS ON PRINTED
CIRCUIT BOARDS FOR NON-VOLATILE
MEMORY DEVICES**

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ABSTRACT

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An electrolytic capacitor can be located in a notch in a side of a PCB with its pins resting on electrical contact pads on the surface of the PCB in a pair of channels in the upper side of the PCB extending away from the sides of the cavity and attached to the contact pads by solder paste. Alternately, the contact pads are on the upper surface of the PCB and the capacitor is located in the cavity with its pins bending upward and then back to be parallel with the upper PCB to attach to the contact pads. The pins and contact pads can be on the same side of the capacitor and cavity or on opposite sides. For smaller devices, such as a ceramic capacitors, a cavity is set into the surface of the PCB and the capacitor's terminals connected to contact pads by wire bonding.

